


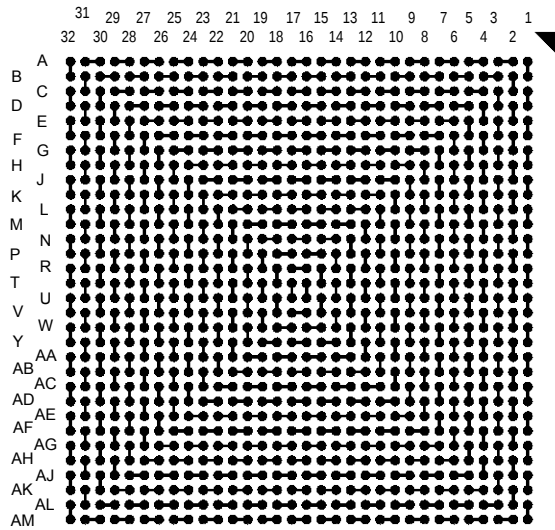
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.35mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.33mm [13 MIL].
- 5) PAD Cu DIAMETER: 0.457mm [18 mil].
- 6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

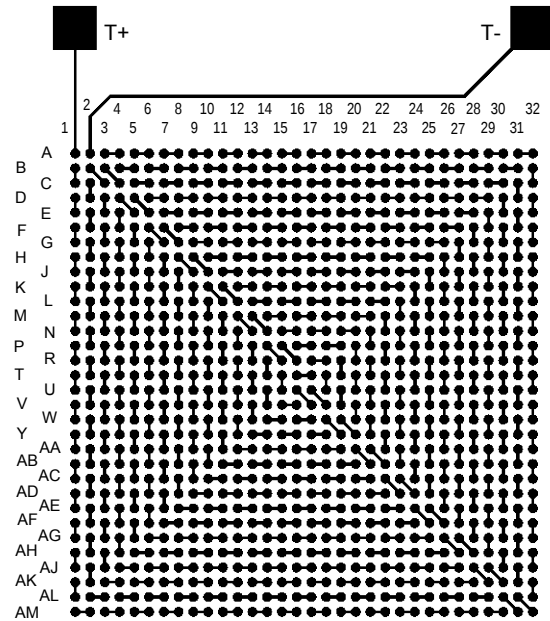
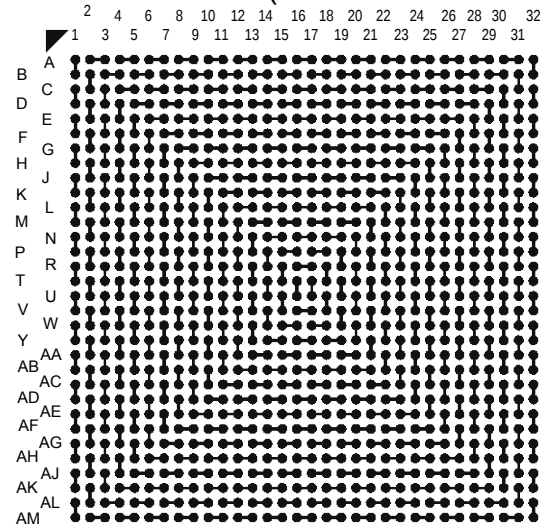
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
SBGA1024T.65C-DC329D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
SBGA1024T.65-DC329D	Sn63/Pb37	Sn63	NO	YES

APPROVALS		DATE				
DRAWN	T. Au	04/30/2019				
ENG	M. Hart	04/30/2019	SCALE		SIZE	DRAWING NO.
MFG			3.5:1		A	563295
QA						REV
CUST						A
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 3

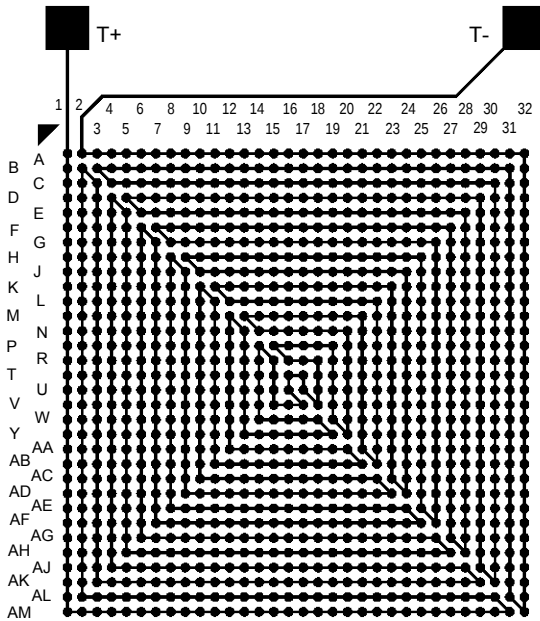
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



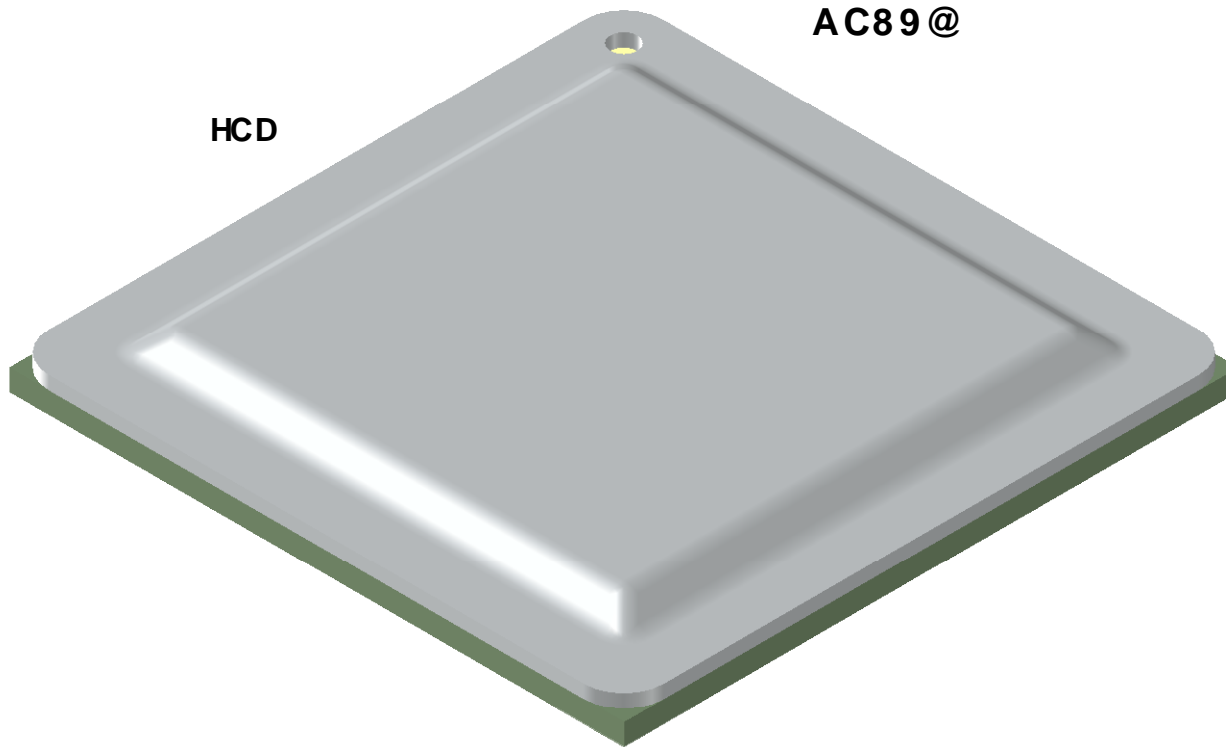
AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.457mm (18 mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm [6 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.33mm [13 MIL].

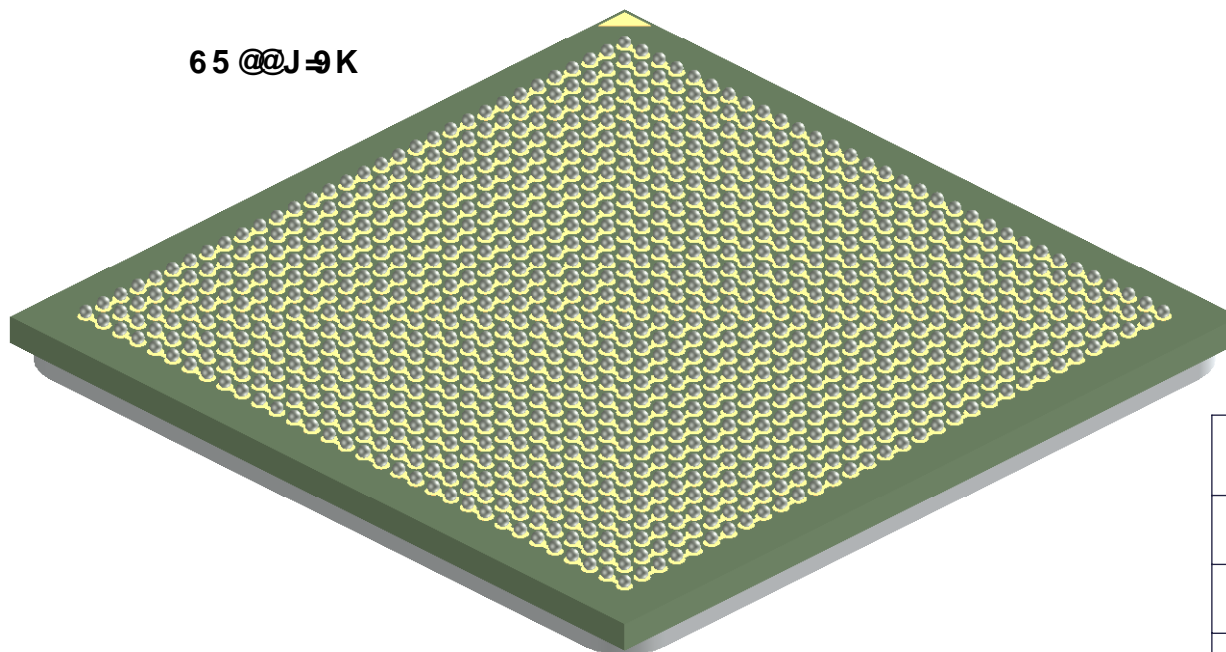


TITLE			
SBGA1024T.65C-DC329D DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.	REV
	A	563295	A
DO NOT SCALE DRAWING			SHEET 2 OF 3



HCD

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TopLine®

TITLE SBGA1024T.65C-DC329D
DAISY CHAIN DUMMY

SCALE	SIZE	DRAWING NO.	REV
	A	563295	A

DO NOT SCALE DRAWING

SHEET 3 OF 3